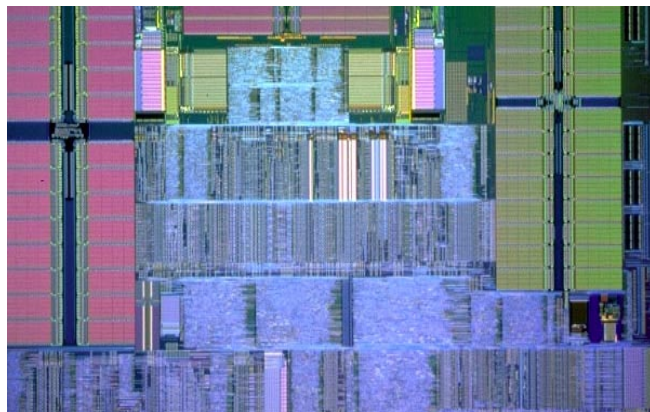
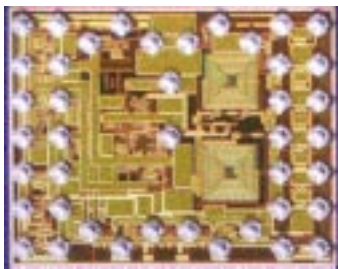


Manufacturing Systems On Silicon (SOC) Containing Mixed Signal Components

Moderator: *James Monzel, IBM*
Panelists: *Ray Bulaga, IBM*
Edmond S. Cooley, Dartmouth
Bozena Kaminska, Opmaxx
Alan Richter, Analog Devices

Over the past few years the levels of integration possible on VLSI devices have enabled volume production of chips containing microprocessors, large SRAM structures, embedded DRAM, embedded flash memory, customer specified logic, and various mixed signal structures. SiGe products have also been developing such that the term System on SiGe may also become a common phrase. Combining mixed signal elements with large digital circuits may produce the worst of both worlds when considering design and test issues. The panelists will each be asked to predict two of the major design and/or test issues that will impede manufacturability of these types of products.



Integrated Mixed
Signal IC, IF?, RF??